

Ultra-Low-Power DC/DC Converters for Battery-Powered and Energy-Harvesting Applications

When Nanoamperes Matter



As battery-powered and energy harvesting applications become more feature-rich, achieving longer battery life and application run time pose serious design challenges. Traditional battery technology cannot keep up with the requirements. Energy harvesters struggle to provide enough energy. Ultra-low-power DC/DC converters from Texas Instruments (TI) help you solve these challenges by enabling peak performance at the lowest power level possible—the nanoampere level. The converters consume the lowest power possible in standby and idle, while still providing high efficiency at very low current levels for longer battery life and application run time.



Key Features and Benefits

- Highest efficiency, >90%, at 10- μ A load current
- Lowest quiescent currents (360 nA typical)
- Selectable output voltages in 100-mV steps with dynamic voltage scaling capability

Featured Ultra-Low-Power DC/DC Converters

Device	Quiescent Current	Special Features	Output Current	Input Range (V)	Packages (mm)
Buck Converters					
TPS62120	11- μ A Iq	Wide UVLO hysteresis window	75 mA	2 to 15	2x2 QFN, SOT23-8
TPS62125	13- μ A Iq	Input SVS (supply voltage supervisor) with adjustable enable threshold and hysteresis	300 mA	3 to 17	2x2 QFN
TPS62743	360 nA	DVS with eight selectable output voltages	300 mA	2 to 5.5	1.6x0.9 8-WCSP
TPS62746	360 nA	Two selectable output voltages (1.2V and 1.8V) with integrated VIN switch	300 mA	2 to 5.5	1.6x0.9 8-WCSP
TPS62748	360nA	Two selectable output voltages (1.2 V and 1.8 V) with integrated load switch	300 mA	2 to 5.5	1.6x0.9 8-WCSP
TPS62770	370nA	Tiny single-chip dual output with 370-nA Iq buck with integrated load switch and up to 15-V dual-mode boost	300-mA for buck, 970-mA switch current limit for boost	2 to 5.5	1.58x1.58 WCSP
TPS62745	400 nA	Dual-cell input, two selectable output voltages with integrated VIN switch	300 mA	3.3 to 10	2x3 QFN
TPS62730	30-nA Iq bypass mode	Bypass mode	100 mA	1.9 to 3.9	1x1.5 QFN
TPS62740	360-nA Iq	DVS and integrated load switch	300 mA	2.2 to 5.5	3x2 QFN
TPS62742	360-nA Iq	DVS and integrated load switch	400 mA	2.2 to 5.5	3x2 QFN
TPS82740	360-nA Iq	DVS and integrated load switch	200 mA	2.2 to 5.5	2.3x2.9 MicroSiP™
Boost Converters					
TPS61291	15-nA Iq in bypass mode 5.5- μ A Iq in boost mode	Bypass switch between VIN and VOUT, pin selectable output voltages(3.3 V, 3 V, 2.5 V)	1-A switch current limit	0.9 to 5	2x2 SON
TPS61251	2- μ A Iq in snooze mode	Adjustable switch current limit	100-mA to 1.5-A adjustable switch current limit	2.3 to 6	2x2 QFN
TPS61220	5.5- μ A Iq	Adjustable output voltage from 1.8 V to 6 V	400-mA switch current limit	0.7 to 5.5	2x1.25 SC-70
TPS61046	110 μ A	Integrated power diode with input/output isolation output up to 28 V	900-mA switch current limit	1.8 to 5.5	0.8x1.2 WCSP
TPS61098/ 981/ 982	300 nA	300-nA dual-output boost converter with integrated LDO with VOUT up to 4.3 V	480-mA switch current limit	0.7 to 4.5	1.5x1.5 6-SON
TPS610985/ 86	300 nA	300-nA dual-output boost converter with integrated load switch	480-mA switch current limit	0.7 to 4.5	1.5x1.5 6-SON
TPS61021	17 μ A	PFM operation in light load, true disconnect between input and output, output range from 1.8 V to 4 V	3-A switch current limit	0.5 to 4.4	2x2 SON

TPS62770

Tiny, Single Chip, Dual Output with 370-nA Iq Step-Down and Dual-Mode Step-Up Converter in WCSP

Key Features

- 90% efficiency at 10- μ A load
- 370-nA Iq step-down converter with integrated load switch
- Dual-mode step-up converter to drive white LED or PMOLED up to 15V
- Eight selectable output voltages for buck converter from 1 V to 3 V
- Slew-rate controlled load switch with discharge function
- Tiny 1.65 x 1.65-mm WCSP package

TPS61098/ 81/ 982/ 85/ 86

300-nA Iq Synchronous Step-Up Converter with Integrated LDO/Load Switch

Key Features

- 88% efficiency at 10- μ A load, 93% at 5-mA to 100-mA load
- Dual output: Boost+LDO/load switch featuring active mode and low-power mode control
- Supports automatic pass-through
- Overload and thermal shutdown protection
- Tiny 1.5 x 1.5-mm WSON package

TPS62743/ 46/ 48

360-nA Iq Step-down Converter in Tiny 8-WSCP

Key Features

- 90% efficiency at 10- μ A load
- Integrated V_{IN} switch (TPS62746)
- Integrated load switch (TPS62743/ 48)
- Eight selectable output voltages (TPS62743)
- Two selectable output voltages (1.2 V and 1.8 V)
- RF friendly DCS-control™ topology
- Tiny 1.6x0.9-mm, 8-ball WCSP package

TPS61021

Ultra-Low Input 3-A Boost Converter

Key Features

- 91% efficiency at $V_{IN} = 2.4$ V, $V_{OUT} = 3.3$ V and $I_{OUT} = 1.5$ -A load
- Input voltage range: 0.5 V to 4.4 V and output voltage range: 1.8 V to 4 V
- $\pm 2.5\%$ reference voltage accuracy over -40°C to 125°C
- True disconnection between input and output during shutdown
- Small 2x2-mm WSON package

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If you want to speed your time to market, check out the TI Designs below. They include comprehensive designs with schematics or block diagrams, BOMs, design files and test reports created by experts with deep system and product knowledge.

Device	Reference Design	Description
TPS62770	PMP9792	Multi-Rail, Low-Iq Power Reference Design for Wearable Applications
TPS61046	PMP11311.5	Power Reference Design for a Wearable Device with Wireless Charging Using the bq51003 and bq25120
TPS62730	TIDC-WMBUS-169 MHz CC1120+TPS62730 CC1120DCDCM868-RD CC2540TPS62730EM-RD CC2541-TPS62730EM-RD	ETSI Cat. 1 Receiver-Capable wM-Bus 169-MHz RF Subsystem for Smart Gas and Water Meters CC1120 with TPS62730 EM 868-MHz and 915-MHz Reference Design CC2540 and TPS62730 (Bluetooth® Low Energy) Evaluation Module Reference Design CC2541-TPS62730EM (Bluetooth Low Energy) Reference Design
TPS62740	PMP9754 TIDM-ULTRASONIC-FLOW-TDC	Solar Dice: A Sensor Node in the Internet of Things (IoT) Reference Design. TPS62740 + CC430 Ultrasonic TDC Flowmeter Reference Design Built using Time-to-Digital Converter and an Ultra-Low-power MCU
TPS62120	PMP5539.2	Isolated Flyback, Bucks (3.3V@35mA) for Consumer Applications

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E2E Power Management Forum: www.ti.com/e2epower

Learn more about TI's complete Ultra-Low-Power DC/DC Converters: www.ti.com/dcdcregulators

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